

# CELCON® LU02

## **CELCON®**

Celcon® acetal copolymer grade LU02 is UV stabilized material displaying a reduced gloss over standard UV acetal grades.

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Resin Identification	POM	ISO 1043
Part Marking Code	>POM<	ISO 11469

### Rheological properties

Melt volume-flow rate	20 cm <sup>3</sup> /10m	in ISO 1133
Temperature	190 °C	
Load	2.16 kg	
Moulding shrinkage, parallel	1.9 %	ISO 294-4, 2577
Moulding shrinkage, normal	1.6 %	ISO 294-4, 2577

### Typical mechanical properties

Tensile modulus	2530	MPa	ISO 527-1/-2
Tensile stress at yield, 50mm/min	56	MPa	ISO 527-1/-2
Tensile strain at yield, 50mm/min	9	%	ISO 527-1/-2
Nominal strain at break	11	%	ISO 527-1/-2
Flexural modulus	2500	MPa	ISO 178
Flexural stress at 3.5%	67	MPa	ISO 178
Charpy notched impact strength, 23°C	3.7	kJ/m²	ISO 179/1eA
Charpy notched impact strength, -30°C	3.7	kJ/m <sup>2</sup>	ISO 179/1eA
Poisson's ratio	0.38 <sup>[C]</sup>		
[C]: Calculated			

# Thermal properties

Melting temperature, 10°C/min	167 °C	ISO 11357-1/-3
Temperature of deflection under load, 1.8 MPa	90 °C	ISO 75-1/-2

## Physical/Other properties

Density	1390 kg/m <sup>3</sup>	ISO 1183
Density	1390 KQ/III <sup>3</sup>	150 1163

### Injection

Drying Recommended	no
Drying Temperature	100 °C
Drying Time, Dehumidified Dryer	3 - 4 h
Processing Moisture Content	≤0.2 %
Melt Temperature Optimum	190 °C
Min. melt temperature	180 °C
Max. melt temperature	195 °C
Screw tangential speed	≤0.3 m/s
Mold Temperature Optimum	90 °C
Min. mould temperature	80 °C
Max. mould temperature	105 °C
Hold pressure range	60 - 120 MPa
Back pressure	4 MPa

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#### Additional information

Injection molding

### Preprocessing

Drying is recommended for low gloss grades of Celcon® and Hostaform® acetal copolymers. Excessive moisture can lead to splay (silver streaking) in molded parts. For better uniformity in molding especially when using regrind or material that has been stored in containers open to the atmosphere, recommended drying conditions are 80 C (180 F) for 3hours. Desiccant hopper dryers are not required. Maximum water content = 0.35%

### **Processing**

Standard reciprocating screw injection molding machines with a high compression screw (minimum 3:1 and preferably 4:1) and low back pressure (0.35 Mpa/50 PSI) are favored. Using a low compression screw (I.E. general purpose 2:1 compression ratio) can result in unmelted particles and poor melt homogeneity. Using a high back pressure to make up for a low compression ratio may lead to excessive shear heating and deterioration of the material.

Use a slow injection speed until material passes through the gate.

Melt Temperature: Preferred range 180-195 C (~356-~383 F). Melt temperature should never exceed 230 C (450 F).

Mold Surface Temperature: Preferred range 80-105 C especially with wall thickness less than 1.5 mm (0.060 in.). May require mold temperature as high as 120 C (250 F) to reproduce mold surface or to assure minimal molded in stress. In general, mold surface temperatures lower than 82 C (180 F) may produce a hazy surface or a surface with flow lines, pits and other included defects.

### Postprocessing

Postprocessing conditioning and moisturizing are not required. It may be necessary to fixture large or complicated parts with varying wall thickness to prevent warpage while cooling to ambient temperature.

**Processing Notes** 

#### **Pre-Drying**

Predrying is required before processing to ensure a low gloss finish.

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